Cheng Qian

List of Publications by Citations

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

34	379	11	18
papers	citations	h-index	g-index

40	523	2.8	3.72
ext. papers	ext. citations	avg, IF	L-index

#	Paper	IF	Citations
34	Thermal Management on IGBT Power Electronic Devices and Modules. *IEEE Access*, **2018**, 6, 12868-12884	3.5	96
33	A novel lifetime prediction for integrated LED lamps by electronic-thermal simulation. *Reliability Engineering and System Safety*, **2017**, 163, 14-21	6.3	27
32	Prediction of Lumen Depreciation and Color Shift for Phosphor-Converted White Light-Emitting Diodes Based on A Spectral Power Distribution Analysis Method. *IEEE Access*, **2017**, 5, 24054-24061	3.5	24
31	Colour shift and mechanism investigation on the PMMA diffuser used in LED-based luminaires. *Optical Materials*, **2016**, 54, 282-287	3.3	23
30	Application of MICMAC, Fuzzy AHP, and Fuzzy TOPSIS for Evaluation of the Maintenance Factors Affecting Sustainable Manufacturing. *Energies*, **2021**, 14, 1436	3.1	22
29	Color Shift Failure Prediction for Phosphor-Converted White LEDs by Modeling Features of Spectral Power Distribution with a Nonlinear Filter Approach. *Materials*, **2017**, 10,	3.5	19
28	Thermal/luminescence characterization and degradation mechanism analysis on phosphor-converted white LED chip scale packages. *Microelectronics Reliability*, **2017**, 74, 179-185	1.2	17
27	Effects of Voids on Mechanical and Thermal Properties of the Die Attach Solder Layer Used in High-Power LED Chip-Scale Packages. *IEEE Transactions on Components, Packaging and Manufacturing Technology*, **2018**, 8, 1254-1262	1.7	16
26	. *IEEE Transactions on Device and Materials Reliability*, **2015**, 15, 576-587	1.6	13
25	Investigation of Step-Stress Accelerated Degradation Test Strategy for Ultraviolet Light Emitting Diodes. *Materials*, **2019**, 12,	3.5	11
24	An Alternative Lifetime Model for White Light Emitting Diodes under Thermal?Electrical Stresses. *Materials*, **2018**, 11,	3.5	11
23	Phosphor�ilicone interaction effects in high power white light emitting diode packages. *Journal of Materials Science: Materials in Electronics*, **2017**, 28, 17557-17569	2.1	11
22	Photometric and Colorimetric Assessment of LED Chip Scale Packages by Using a Step-Stress Accelerated Degradation Test (SSADT) Method. *Materials*, **2017**, 10,	3.5	11
21	Application of artificial neural networks for quantitative damage detection in unidirectional composite structures based on Lamb waves. *Advances in Mechanical Engineering*, **2020**, 12, 168781402091473	1.2	10
20	A Gamma Process-Based Prognostics Method for CCT Shift of High-Power White LEDs. *IEEE Transactions on Electron Devices*, **2018**, 65, 2909-2916	2.9	10
19	. *IEEE Access*, **2019**, 7, 68495-68502	3.5	8
18	Numerical Thermal Analysis and Optimization of Multi-Chip LED Module Using Response Surface Methodology and Genetic Algorithm. *IEEE Access*, **2017**, 5, 16459-16468	3.5	8

List of Publications

17	**2016**,		6
16	. *IEEE Photonics Journal*, **2020**, 12, 1-18	1.8	4
15	A design and qualification of LED flip Chip-on-Board module with tunable color temperatures. *Microelectronics Reliability*, **2018**, 84, 140-148	1.2	4
14	Experimental Investigation on the Sintering Kinetics of Nanosilver Particles Used in High-Power Electronic Packaging. *IEEE Transactions on Components, Packaging and Manufacturing Technology*, **2020**, 10, 1101-1109	1.7	4
13	High Temperature Performance Evaluation and Life Prediction for Titanium Modified Silicone Used in Light-Emitting Diodes Chip Scale Packages. *Journal of Electronic Packaging, Transactions of the ASME*, **2020**, 142,	2	4
12	Studies of the light output properties for a GaN based blue LED using an electro-optical simulation method. *Microelectronics Reliability*, **2017**, 74, 173-178	1.2	3
11	An Archimedean Copula Function-Based Prediction Method for High-Power White LED Considering Multi-Performance. *IEEE Transactions on Electron Devices*, **2019**, 66, 3405-3410	2.9	3
10	Investigation of photoluminescence and thermal effect of phosphor films used in phosphor-converted white LEDs **2015**,		3
9	Characterization and reconstruction for stochastically distributed void morphology in nano-silver sintered joints. *Materials and Design*, **2020**, 196, 109079	8.1	2
8	Analysis of photoluminescence mechanisms and thermal quenching effects for multicolor phosphor films used in high color rendering white LEDs **2016**,		2
7	Characterization of Stochastically Distributed Voids in Sintered Nano-Silver Joints **2019**,		1
6	A Heuristic Hybrid Optimization Approach for Spare Parts and Maintenance Workers Under Partial Pooling. *IEEE Access*, **2019**, 7, 137835-137847	3.5	1
5	Study of ultraviolet assisted cure mechanism of the phosphor/silicone composites used in White LEDs **2018**,		1
4	Tensile characterization and constitutive modeling of sintered nano-silver particles over a range of strain rates and temperatures. *Microelectronics Reliability*, **2022**, 132, 114536	1.2	1
3	An Electric Fence-Based Intelligent Scheduling Method for Rebalancing Dockless Bike Sharing Systems. *Applied Sciences (Switzerland)*, **2022**, 12, 5031	2.6	1
2	Degradation Analysis for Reliability of Optoelectronics **2022**, 317-350		
1	PHM of Light-Emitting Diodes **2018**, 377-430		